

Title (en)
PROCESS AND DEVICE FOR CONTINUOUS TREATMENT OF A WEB SUBSTRATE

Title (de)
VERFAHREN UND VORRICHTUNG ZUR KONTINUIERLICHEN BEHANDLUNG EINES BAHNSUBSTRATS

Title (fr)
PROCÉDÉ ET DISPOSITIF DE TRAITEMENT CONTINU D'UN SUBSTRAT EN NAPPE

Publication
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Application
EP 06812769 A 20061006

Priority
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Abstract (en)
[origin: WO2008041858A1] A process and a device system for continuous treatment of a web substrate (7), after printing processes and integrated between printer technologies and finishing processes, comprising a control device (1) ensuring a correct feeding tension and sufficient buffer capacity of the substrate, tempering the substrate to ensure a desired temperature in the substrate, coating the substrate by aggregates in a feeding system (6), controlling the substrate temperature, the relative substrate humidity, the static substrate load as well as the coating thickness, volume of the substrate and the roller pressures of the aggregates by a computer based on readings from sensors along the path of the substrate, depending on the speed by which the substrate is leaving the previous printing process.

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Citation (search report)

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